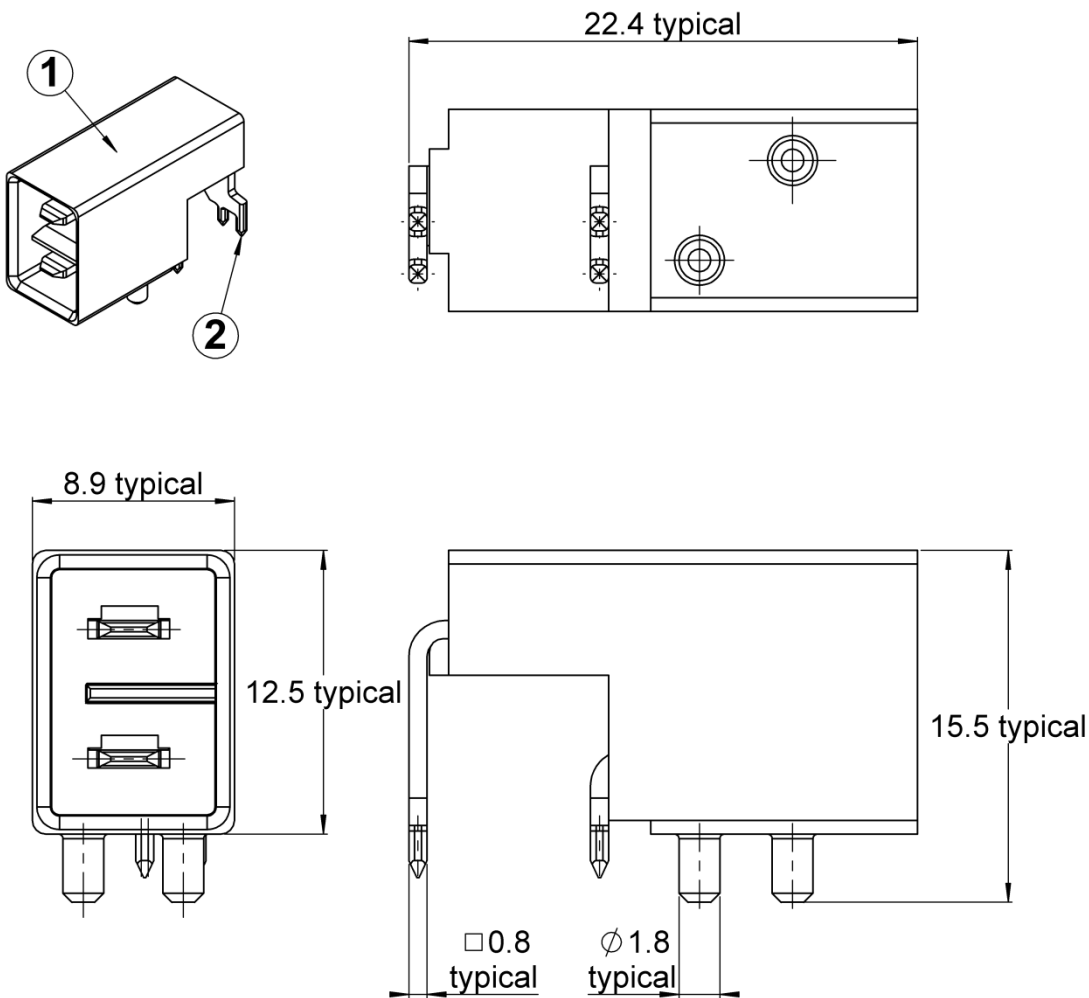


| | | | |
|----------|-----------------|--------------|------------------------|
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|----------|-----------------|--------------|------------------------|



All dimensions are 8in mm. Unmarked tolerance is ±0.3mm

DESCRIPTION

| REP | COMPONENT | MATERIALS | PLATING |
|-----|-----------|--------------|---------|
| 1 | Housing | PLASTIC | - |
| 2 | Contact | COPPER ALLOY | SN |

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GENERAL CHARACTERISTICS

| | | |
|--|--|--|
| Mechanical Mating endurance (cycles) Vibration Weight (g) | IEC 61300-2-2 EIA 364-28 - | 100 - 2.573 |
| Environmental Operating temperature (°C) Storage temperature (°C) RoHS Flammability | IEC 61300-2-22 IEC 61300-2-22 - UL 94 | -40 / +85 -65 / +85 Compliant V0 |
| Electrical Working voltage Current rating (A) Dielectric withstanding voltage Insulation resistance | - - EIA 364-20 EIA 364-21 | Max. 300V AC (r.m.s.) 16A with 16AWG wire (stranded) 20A with 14AWG & 12AWG wire (stranded) 30A with 10AWG wire (stranded) 500V AC 5000MΩ minimum initial 1000MΩ minimum after environmental aging |
| Others OCTIS Plug Packaging | - - | For use with OCTI3175xx or OCTI3275xx Packaging in Tape & Reel, 185 per reel. |

(*) Mated condition

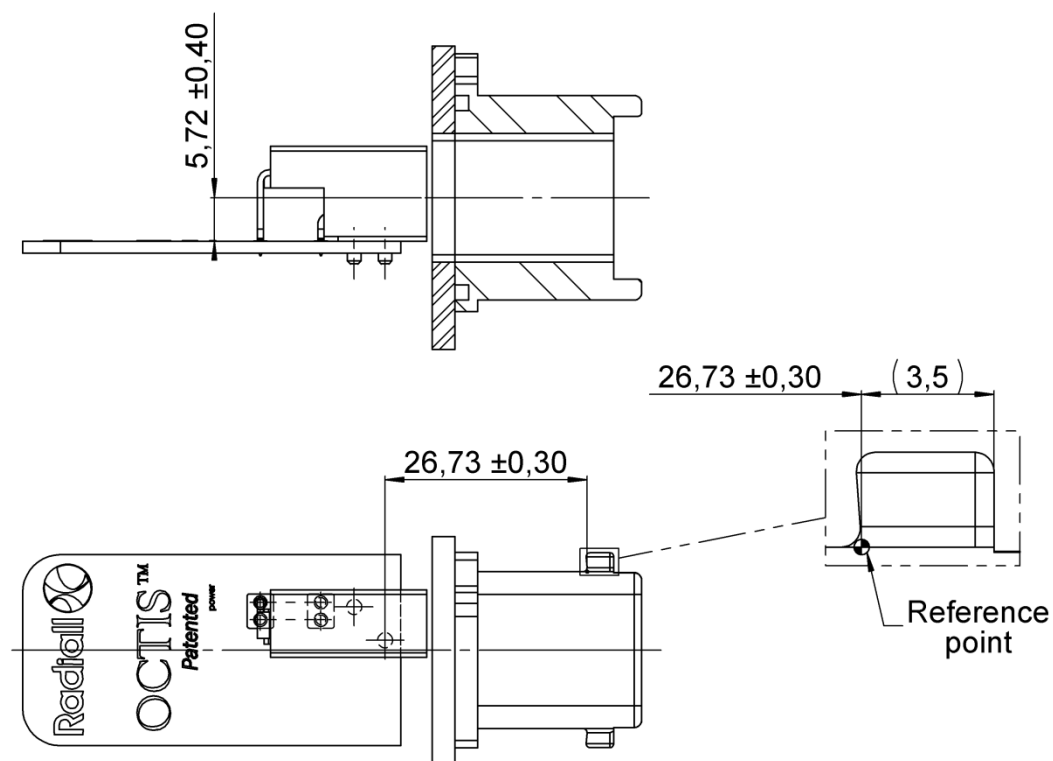
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POSITIONING AND PATTERN DEFINITION



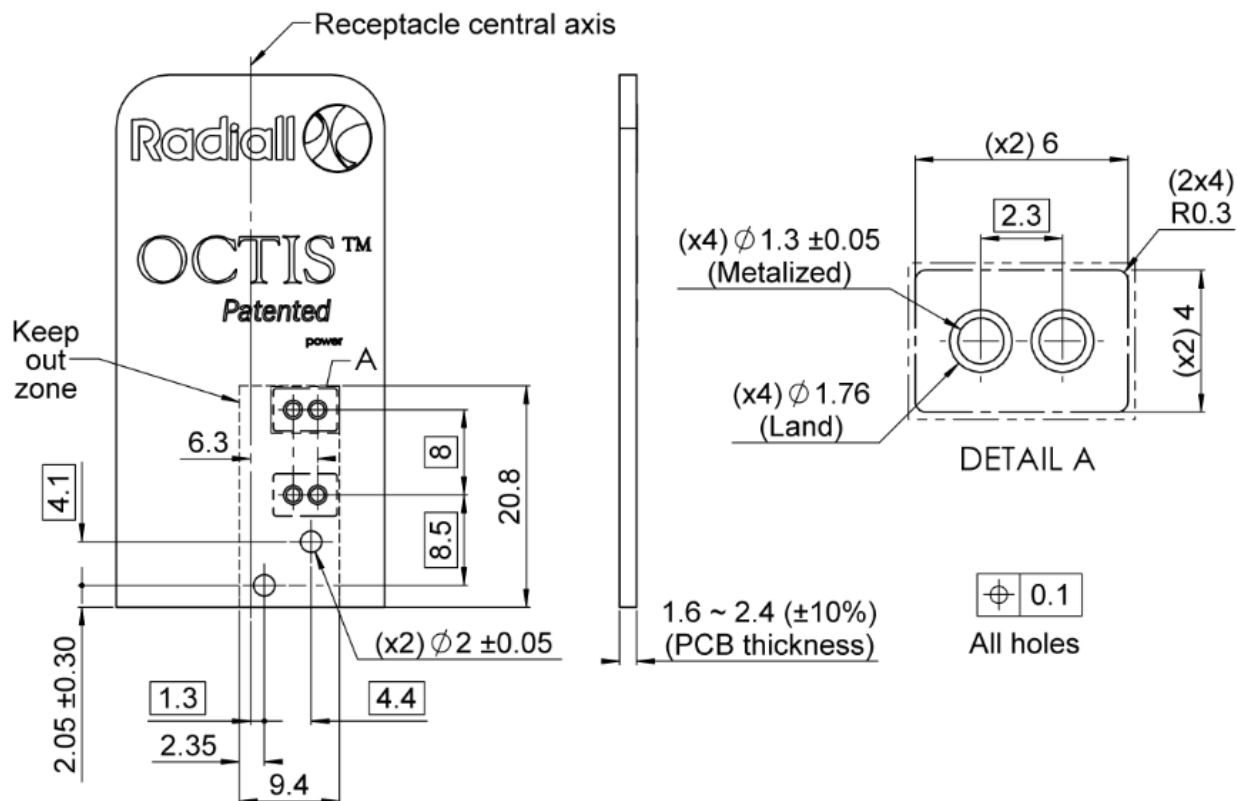
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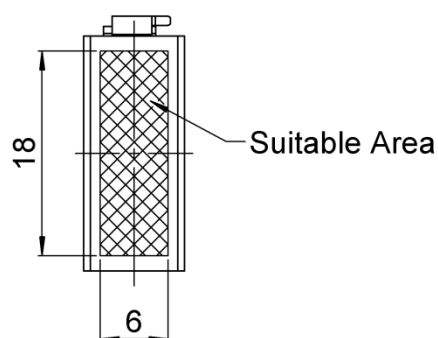
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FOOT/PRINT (General tolerance for PCB ± 0.1 mm)



SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



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SERIES OCTIS

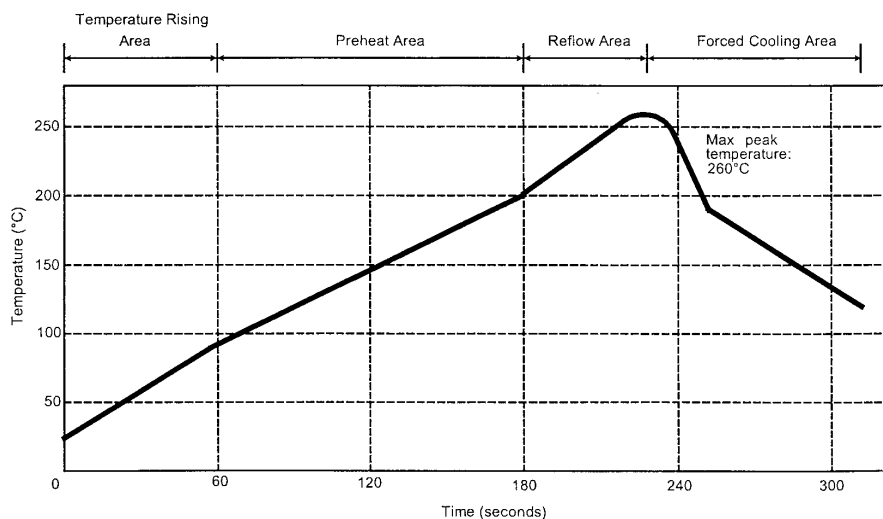
PART NUMBER OCTI360500

SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine. A video camera is recommended for a good positioning of the component. Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven. Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



| Parameter | Value | Unit |
|----------------------------------|-----------|--------|
| Temperature rising Area | 1 to 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |

* Typical data for reflow process. Alternatively, wave soldering is also possible